

Supporting Information

Tunable Piezoresistivity of Low Percolation Threshold Micro-Nickel Wires/PDMS Conductive Composite Regulated by Magnetic Field

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1. The electrodes used during the assembly and package of the sensor

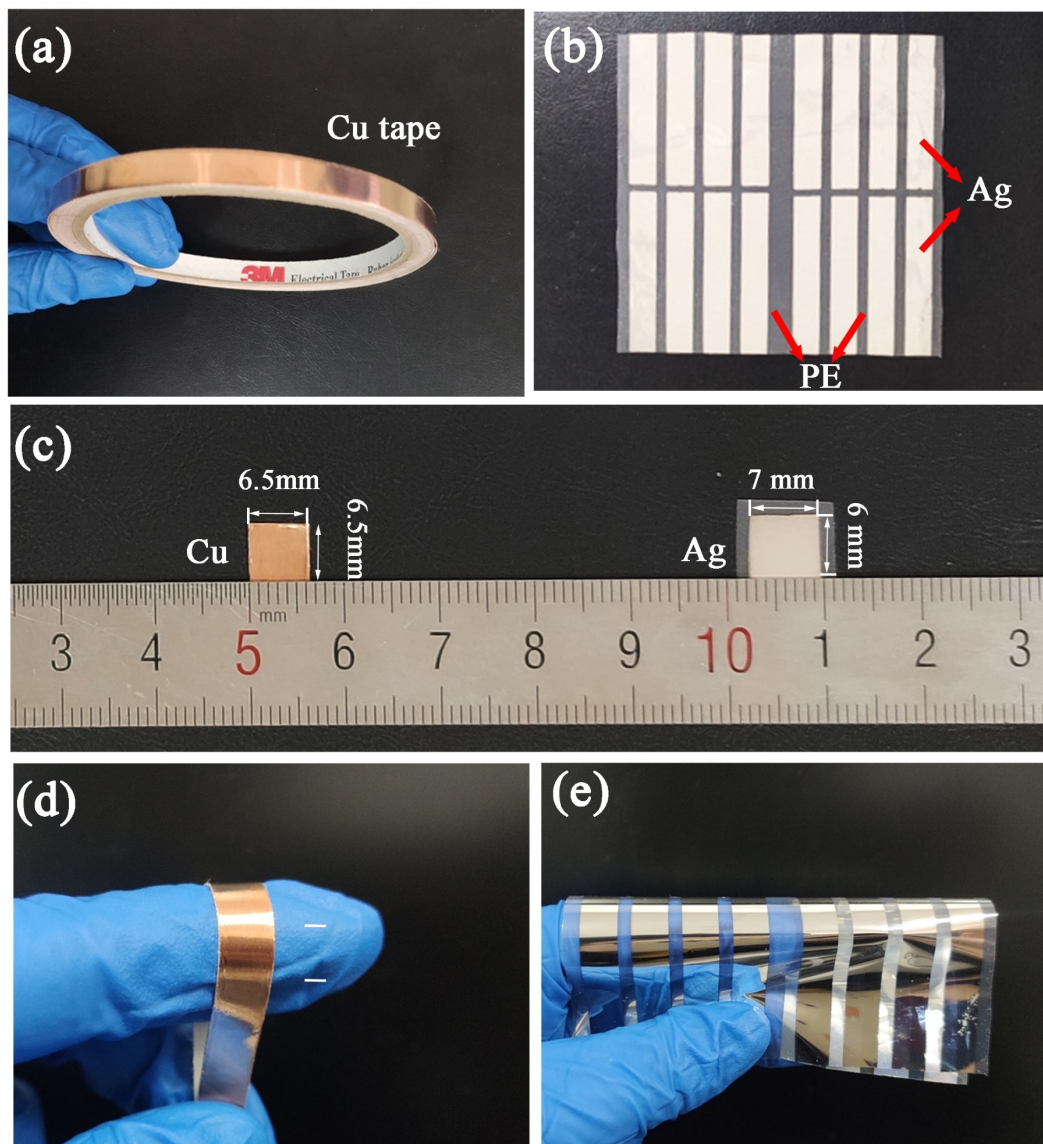


Fig. S1. Photographs of (a) conductive Cu tape and (b) Ag electrodes deposited on PE film. (c) Dimensions of Cu electrode and Ag electrode. (d) Photograph of Cu electrodes under bending conditions. (e) Photograph of Ag electrodes deposited on PE substrate under bending conditions.

2. The packaging steps of the sensor used for the demonstration

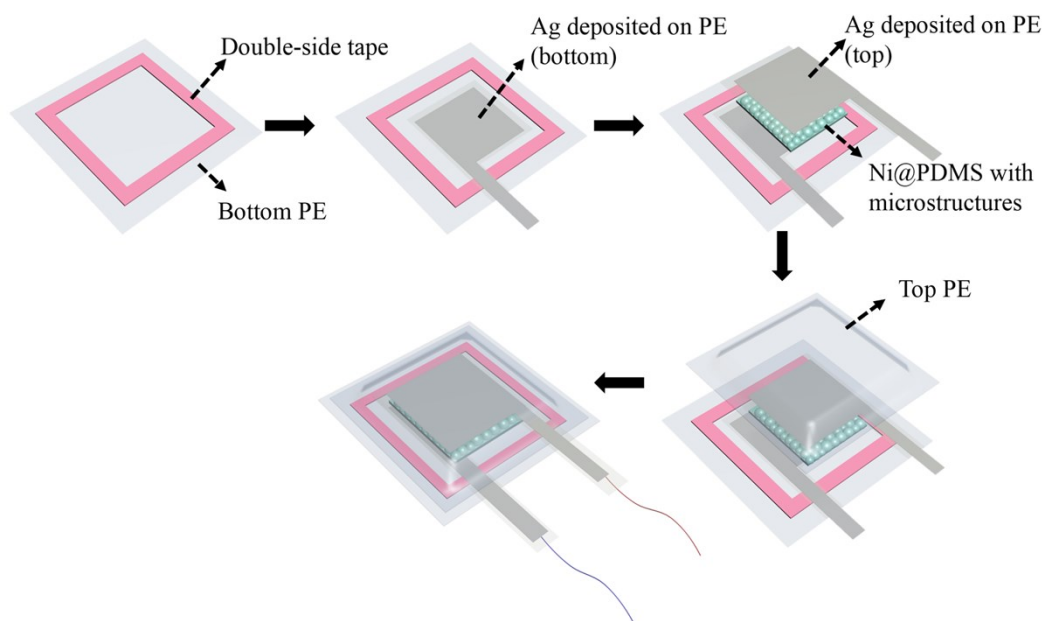


Fig. S2. Schematic diagram of encapsulation steps of the piezoresistive sensor based on Ni@PDMS composite with microhump structures.

3. The exhibition of flexibility of the packaged sensor

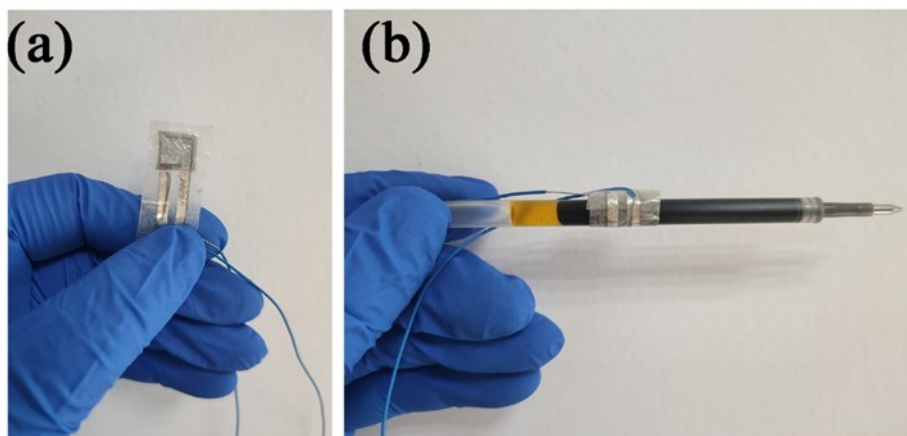


Fig. S3. (a) Photograph of a packaged piezoresistive pressure sensor based on Ni@PDMS composite with microhump structures. (b) The sensor could be completely rolled onto a cartridge.